

PCB Stick-to-it-ive-ness.

Yes We Can. With MultiPrep.



When it comes to revolutionary advancements in copper adhesion, uniformity and cosmetics, only MacDermid Electronics Solutions puts you in the driver's seat. Our MultiPrep process, engineered after decades of etching experience, delivers an unparalleled copper surface prep for multiple applications, especially solder mask, dry film and liquid photoresists. It also eliminates pumice and brush scrubbing for improved efficiency, all while maintaining high-speed signal integrity. MultiPrep is not just an evolution, but a ground-breaking innovation.

For the surface that sticks and grips, count on the company that says "Yes We Can." MacDermid



Metallization • Circuit Formation • Imaging Systems • Final Finishes • Interconnect • Emerging Technologies

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